

Electronic Patent Application Fee Transmittal

Application Number:	10680509			
Filing Date:	07-Oct-2003			
Title of Invention:	Adhesive bonding with low temperature grown amorphous or polycrystalline compound semiconductors			
First Named Inventor/Applicant Name:	Kuang Chien Hsieh			
Filer:	Mindy Niedzielka Rittner/Corinne Roempagel			
Attorney Docket Number:	10322/57			
Filed as Small Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Independent claims in excess of 3	2201	3	105	315
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				315